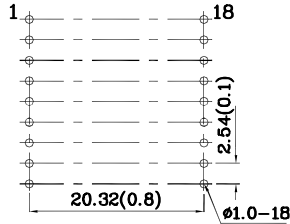


**Features**

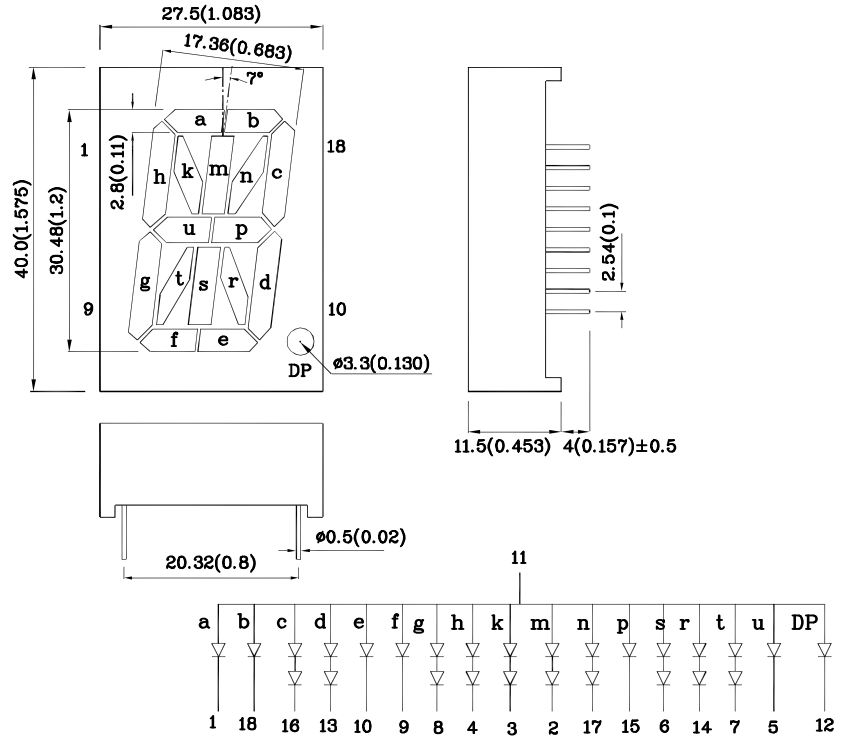
- Low power consumption
- Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant



**RECOMMENDED PCB LAYOUT**



**Package Schematics**



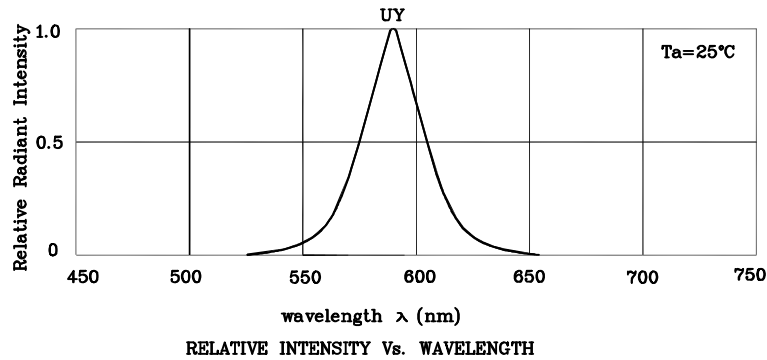
**Notes:**

1. All dimensions are in millimeters (inches), Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
2. Specifications are subject to change without notice.

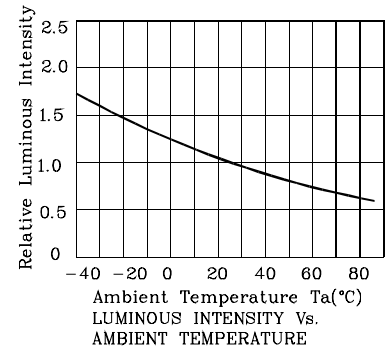
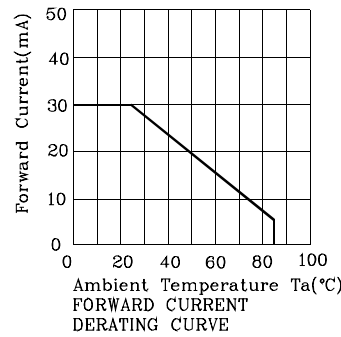
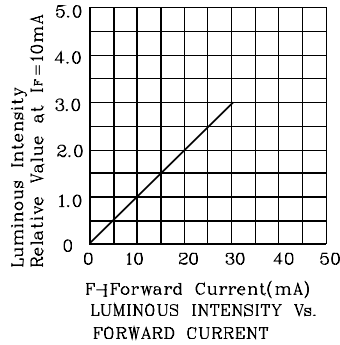
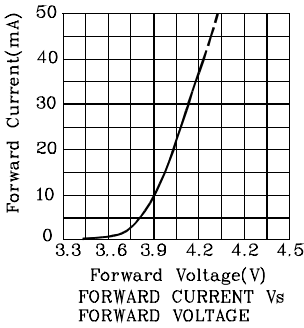
Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ )			UY (GaAsP/ GaP)	Unit
Reverse Voltage	c,d,g,h,k,m,n, s,r,t	$V_R$	5	V
	a,b,e,f,p,u and DP		5	
DC Forward Current	c,d,g,h,k,m,n, s,r,t	$I_F$	30	mA
	a,b,e,f,p,u and DP			
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	c,d,g,h,k,m,n, s,r,t	$i_{FS}$	140	mA
	a,b,e,f,p,u and DP			
Power Dissipation	c,d,g,h,k,m,n, s,r,t	$P_D$	150	mW
	a,b,e,f,p,u and DP		75	
Operating Temperature	$T_A$		-40 ~ +85	$^\circ\text{C}$
Storage Temperature	$T_{stg}$		-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]			260 $^\circ\text{C}$ For 3~5 Seconds	

Operating Characteristics ( $T_A=25^\circ\text{C}$ )			UY (GaAsP/ GaP)	Unit
Forward Voltage (Typ.) ( $I_F=10\text{mA}$ )	c,d,g,h,k,m,n, s,r,t	$V_F$	3.9	V
	a,b,e,f,p,u and DP		1.95	
Forward Voltage (Max.) ( $I_F=10\text{mA}$ )	c,d,g,h,k,m,n, s,r,t	$V_F$	5	V
	a,b,e,f,p,u and DP		2.5	
Reverse Current (Max.) ( $V_R=5\text{V}$ )	c,d,g,h,k,m,n, s,r,t	$I_R$	10	$\mu\text{A}$
	a,b,e,f,p,u and DP			
Wavelength of Peak Emission (Typ.) ( $I_F=10\text{mA}$ )	$\lambda_P$		590	nm
Wavelength of Dominant Emission (Typ.) ( $I_F=10\text{mA}$ )	$\lambda_D$		588	nm
Spectral Line Full Width At Half- Maximum (Typ.)( $I_F=10\text{mA}$ )	$\Delta\lambda$		35	nm
Capacitance (Typ.) ( $V_F=0\text{V}$ , $f=1\text{MHz}$ )	C		20	pF

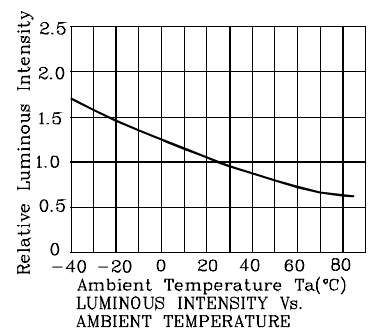
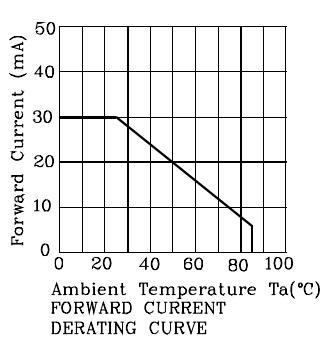
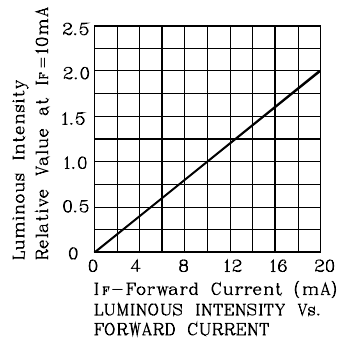
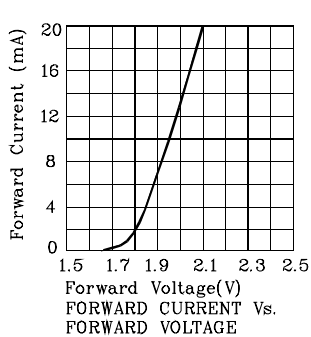
Part Number	Emitting Color	Emitting Material	Luminous Intensity (If=10mA) ucd		Wavelength nm λP	Description
			min.	typ.		
XAUY30A	Yellow	GaAsP/GaP	2200	5890	590	Common Anode, Rt. Hand Decimal.



❖ **UY**

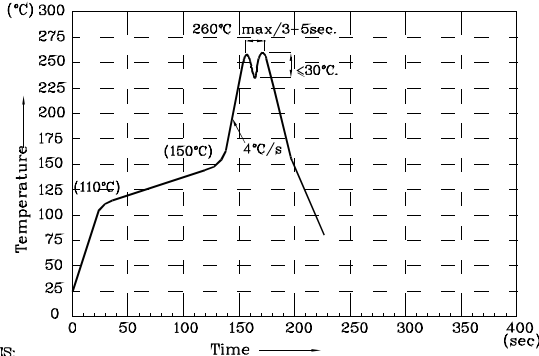


Note:the curves are on the segment c,d,g,h,k,m,n,s,r and t.



Note:the curves are on the segment a,b,e,f,p,u and DP.

Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

- 1.Recommum the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering, the PCB top-surface temperature should be kept below 105°C.
- 5.No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

